

IN THE CLAIMS:

Please amend the claims as shown below. The status of the claims after amendment will be as follows:

1. (previously presented) A cap-shaped lid for use with a generally flat base to seal an electronic device comprising a top portion, a wall structure extending around an entire periphery of the top portion and having an upper end connected to the top portion and a lower end, a lip connected to the lower end of the wall structure around an entire periphery of the wall structure and extending outwards from an outer surface of the wall structure by 10 - 500 μm , and solder applied to an inner surface of the lid on at least a portion of the lip.

2. (original) A lid as claimed in claim 1 wherein the lip is curved with respect to the wall structure.

3. (original) A lid as claimed in claim 1 wherein the top surface of the lid is polygonal.

4. (previously presented) A lid as claimed in claim 1 wherein the wall structure extends substantially perpendicularly with respect to the top surface.

5. (previously presented) A lid as claimed in claim 1 wherein solder is provided on the entire inner surface of the

lid.

6. (currently amended) A packaged electronic part comprising a generally flat base, an electronic device mounted on a top surface of the base, and a cap-shaped lid according to claim 1 covering the electronic device and soldered to the top surface of the base and hermetically sealing the electronic device inside the package.

7. (withdrawn) A method of manufacturing a cap-shaped lid as claimed in claim 1 comprising performing drawing of a metal sheet having solder on a first side of the metal sheet to form a recessed shape including the top portion, the wall structure, and a flange extending outwards from the wall structure with the first side of the metal strip on the interior of the recessed shape, and then severing the flange around an entire periphery of the recessed shape at a distance of 10 - 500 μm from an outer side of the wall structure to define the lip.

8. (withdrawn) A method as claimed in claim 7 including severing the flange with a punch.

9. (withdrawn) A method as claimed in claim 7 including severing the flange in a portion which is curved with respect to the wall structure.

Claim 10 (cancelled)

11. (previously presented) A lid as claimed in claim 1 wherein the wall structure, the top portion, and the lip are formed from a single metal sheet.

12. (currently amended) A lid as claimed in claim 5 wherein the solder comprises a layer of solder formed on the inner surface of the wall structure by hot dipping.

13. (new) A lid as claimed in claim 1 wherein the wall structure, the top portion, and the lip are without openings through which air can pass.

14. (new) A lid as claimed in claim 1 wherein the lip extends outwards from the outer surface of the wall structure by 10 - 100 μm .

15. (new) A packaged electronic part as claimed in claim 6 wherein the lid is connected to the base by a solder joint including solder which has flowed downwards from an inner surface of the wall structure towards the base.

16. (new) A packaged electronic part as claimed in claim 6 wherein the lid has a hot dipped solder layer formed on the lip and an inner surface of the wall structure, and the lid is soldered to the top surface of the base so as to form a hermetic seal by solder in the solder layer.